

O I P E J C & Co.
OCT 03 2002
PATENT & TRADEMARK OFFICE
Express Mail Label EL393527360US

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: WAYNE J. SCHMIDT, ROBERT
BERNER, AND DANIEL J. WOODRUFF

APPLICATION No.: 08/680,067

FILED: July 15, 1996

FOR: PLATING SYSTEM FOR SEMICONDUCTOR
MATERIALS

EXAMINER: W. LEADER
ART UNIT: 1741
CONF. NO: N/A

RESPONSE TO OFFICE ACTION UNDER 37 C.F.R. § 1.111

Assistant Commissioner for Patents
Washington, D.C. 20231

RECEIVED
OCT 07 2002

OFFICE OF PETITIONS

Sir:

This paper is filed with a Petition to Revive a Patent Application under 37 C.F.R. § 1.137(b) in response to the Office Action dated March 21, 2001. In accordance with 37 C.F.R. § 1.121, all of the pending claims are set forth below, and any amendments to the claims are shown in the attached appendix.

In the Claims:

Following is a complete listing of the claims pending in the application:

40. A workpiece processing apparatus, comprising:
an apparatus frame;
a processing fluid supply;
a process bowl;
a fluid cup disposed within said process bowl and defining a fluid flow region between an outer sidewall of the fluid cup and an inner sidewall of the process bowl, the fluid cup including an upper rim forming an overflow weir over which processing fluid can enter the fluid flow region, said fluid